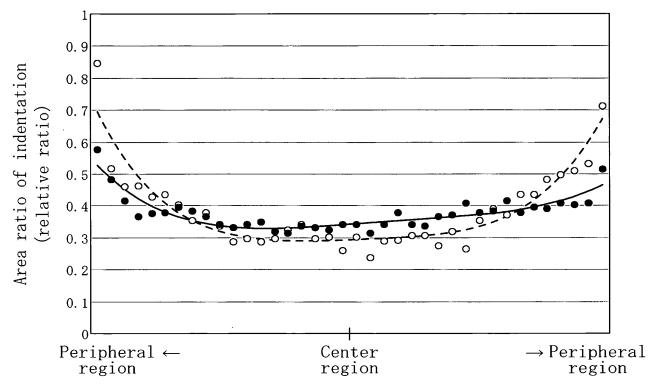
↓ Deforming 101 113 118 112 115 103 110a 101a

FIG. 1

FIG. 2



Position in semiconductor wafer plane



FIG. 3A

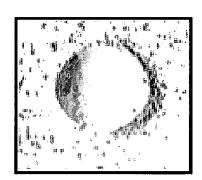


FIG. 3B

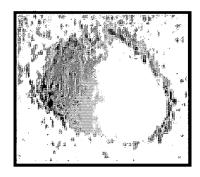


FIG. 3C

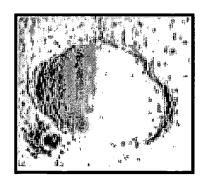




FIG. 4

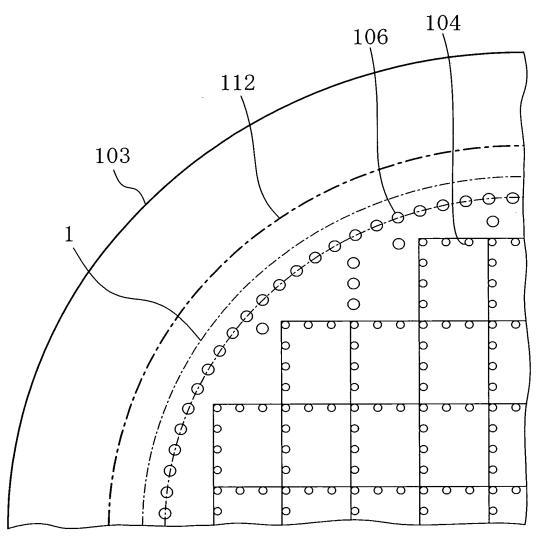
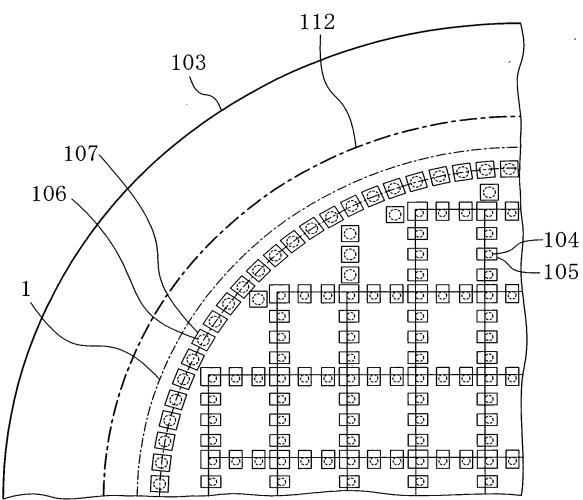




FIG. 5

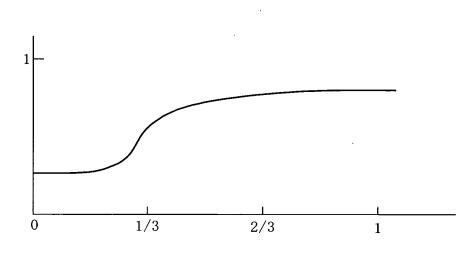




Indentation area of outermost bump

Indentation area of center bump





Pressing force applied to all isolated patterns

Pressing force applied to all electrically connecting isolated patterns



FIG. 7
PRIOR ART

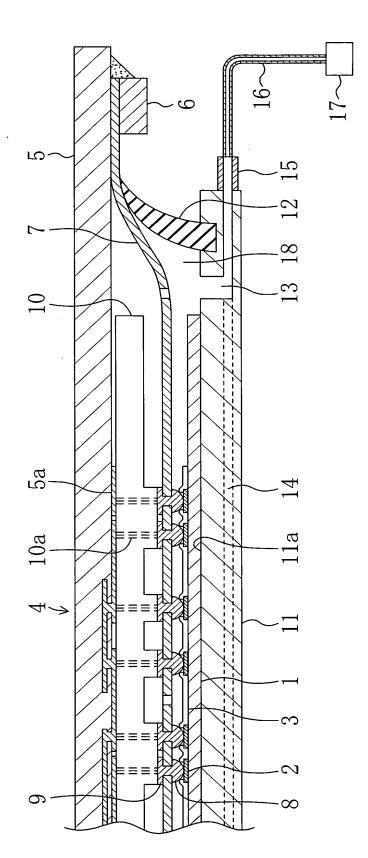
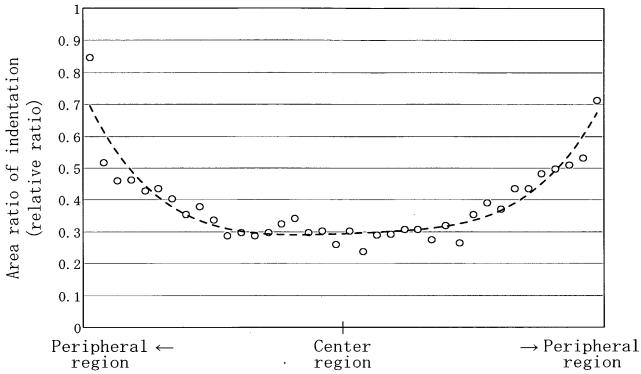




FIG. 8 PRIOR ART



Position in semiconductor wafer plane



FIG. 9A PRIOR ART

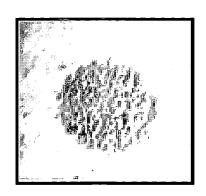


FIG. 9B PRIOR ART

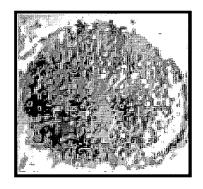


FIG. 9C PRIOR ART

